



Advantest IR Technical Briefing

# **Demand Changes and Our Solutions in System Level Test (SLT)**

June 26<sup>th</sup>, 2020

Yasuo Mihashi

Managing Executive Officer

Executive Vice President, Corporate Relations Group

# NOTE

---

## Cautionary Statement with Respect to Forward-Looking Statements

- This presentation contains “forward-looking statements” that are based on Advantest’s current expectations, estimates and projections. These statements include, among other things, the discussion of Advantest’s business strategy, outlook and expectations as to market and business developments, production and capacity plans. Generally, these forward-looking statements can be identified by the use of forward-looking terminology such as “anticipate,” “believe,” “estimate,” “expect,” “intend,” “project,” “should” and similar expressions. Forward-looking statements are subject to known and unknown risks, uncertainties and other factors that may cause Advantest’s actual results, levels of activity, performance or achievements to be materially different from those expressed or implied by such forward-looking statements.

## Use of These Materials

- The information contained in this presentation is protected under intellectual property laws, such as copyright law, patent law, trademark law and design law, and other laws and statutes of each country and various treaties. Any use (modification, copying, diversion, etc.) of this information that goes beyond that which is clearly authorized by law and statutes, and is not approved in writing by our company in advance, is forbidden.

# Today's Agenda

---

- ✓ Changes in Business Environment of System Level Test (SLT)
- ✓ Opportunities in the “New” SLT Market
- ✓ Summary



# Changes in Business Environment of System Level Test (SLT)

---

# Our Grand Design (FY2018 - FY2027)

Background: Change in the Tester Market

## PAST

Mainframes → PCs  
→ Smartphones

- Smaller, Cheaper
- Greater Tester Efficiency



## FUTURE

Data Takes the Spotlight  
Semiconductors as Infrastructure

- Greater Semiconductor Functionality, Complexity, Capacity
- High Reliability

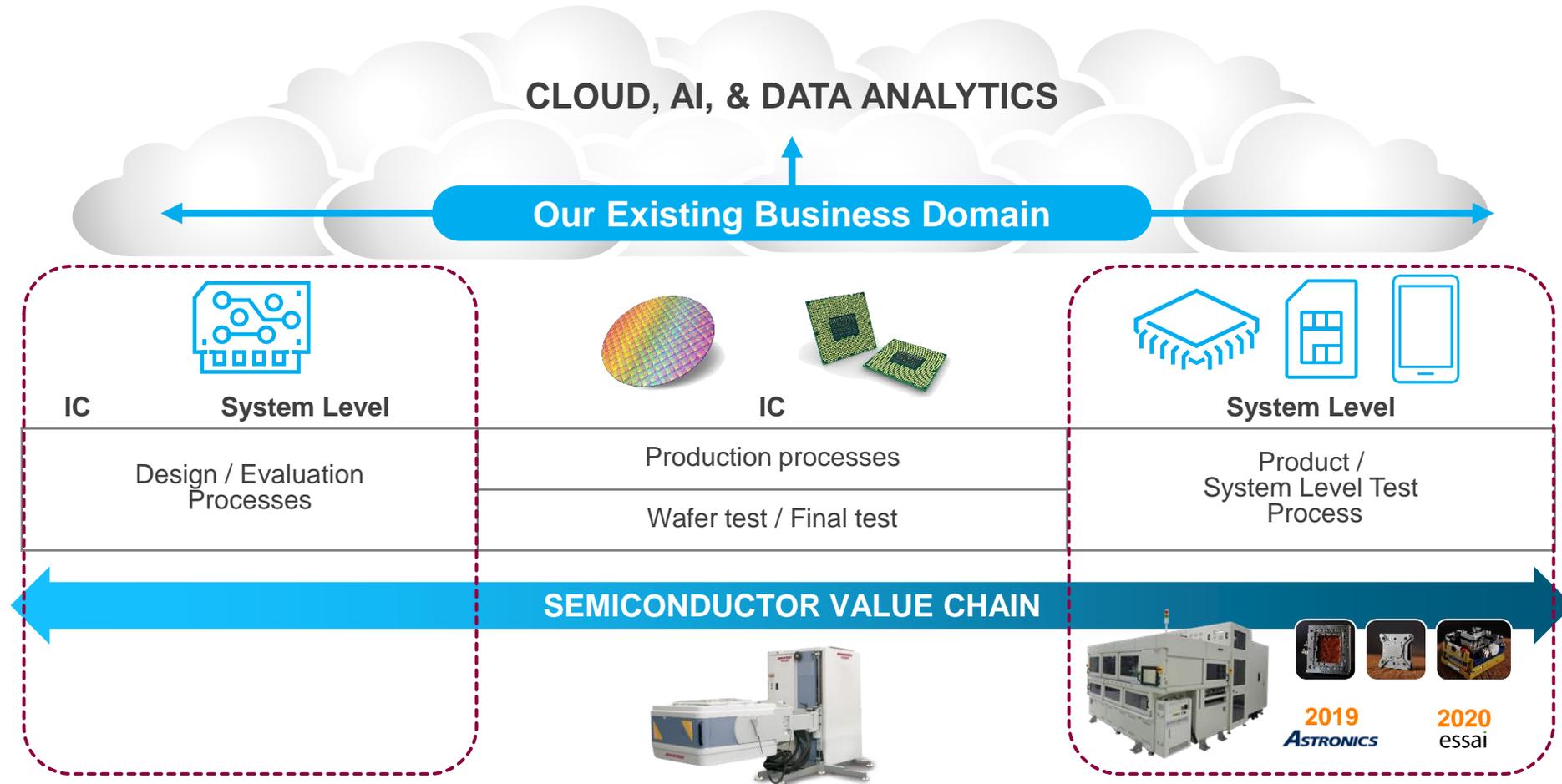


More Test Items & Longer Test Times × Greater Difficulty of Failure Detection  
= Test to be Reinforced to Guarantee Reliability

**Test will Become More Important and More of them will be Needed**

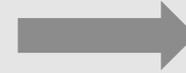
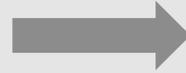
# Adding Customer Value in an Evolving Semiconductor Value Chain

Grand Design: Our Vision



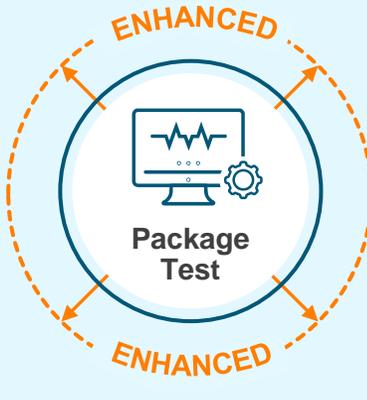
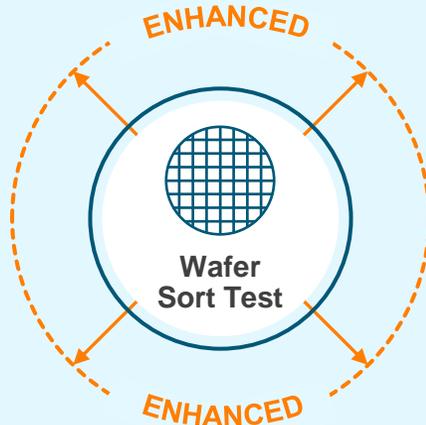
# Changes in the Test Flow for High-end SoCs

PAST



SLT was limited to few applications only

NOW

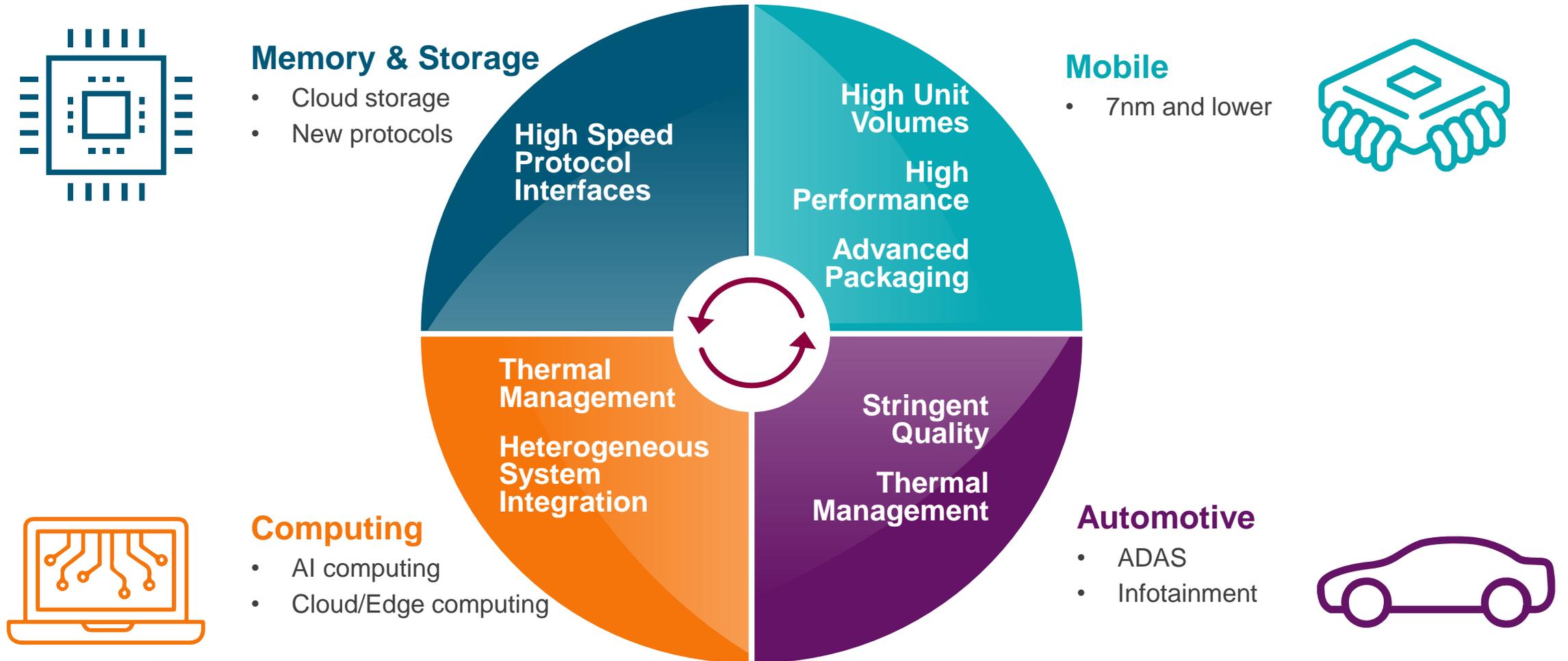


SLT is being adopted for "Mission Critical" applications with fully integrated manner

Chip test enhancement driven by adoption of multiple test process and longer test time, more complex IP and roll out of advanced packages

Advanced technology is driving changes in test requirements and the test flow

# Market Mega Trends Driving System Level Test



**Those Mission Critical Applications are our SLT Market**

# Voice of Customers

---

“High volume  
production System  
Level Testing”

“World class  
DPPM needed”

“Applications with  
thermal control to  
guarantee quality”

“Multi-IP testing  
under system  
load with thermal  
control”

“Complex power  
management  
features during  
system operation”

“High-speed  
interface testing”



# Opportunities in the “New” SLT Market

All Rights Reserved - ADVANTEST CORPORATION

**ADVANTEST**<sup>®</sup>

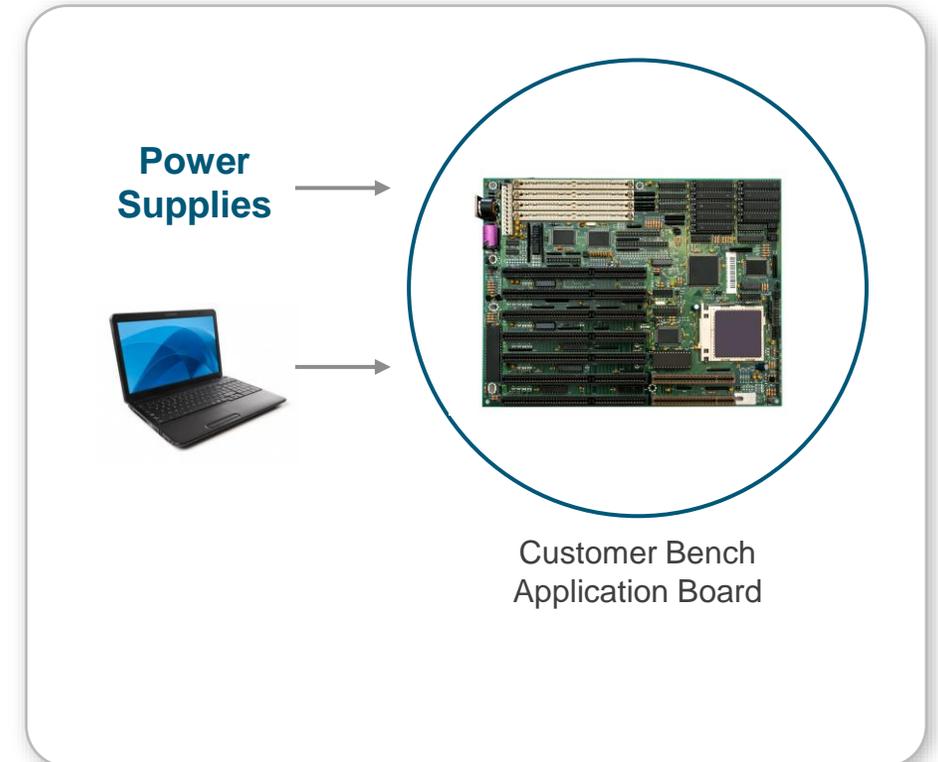
# What is Conventional System Level Test (SLT)?

## Example : GPU for Server

- IC (DUT) is temporarily placed in a socket on the Customer Bench Application Board
- PC with software and power supplies are connected to Application board
- Tests similar to end user scenario are run with real software

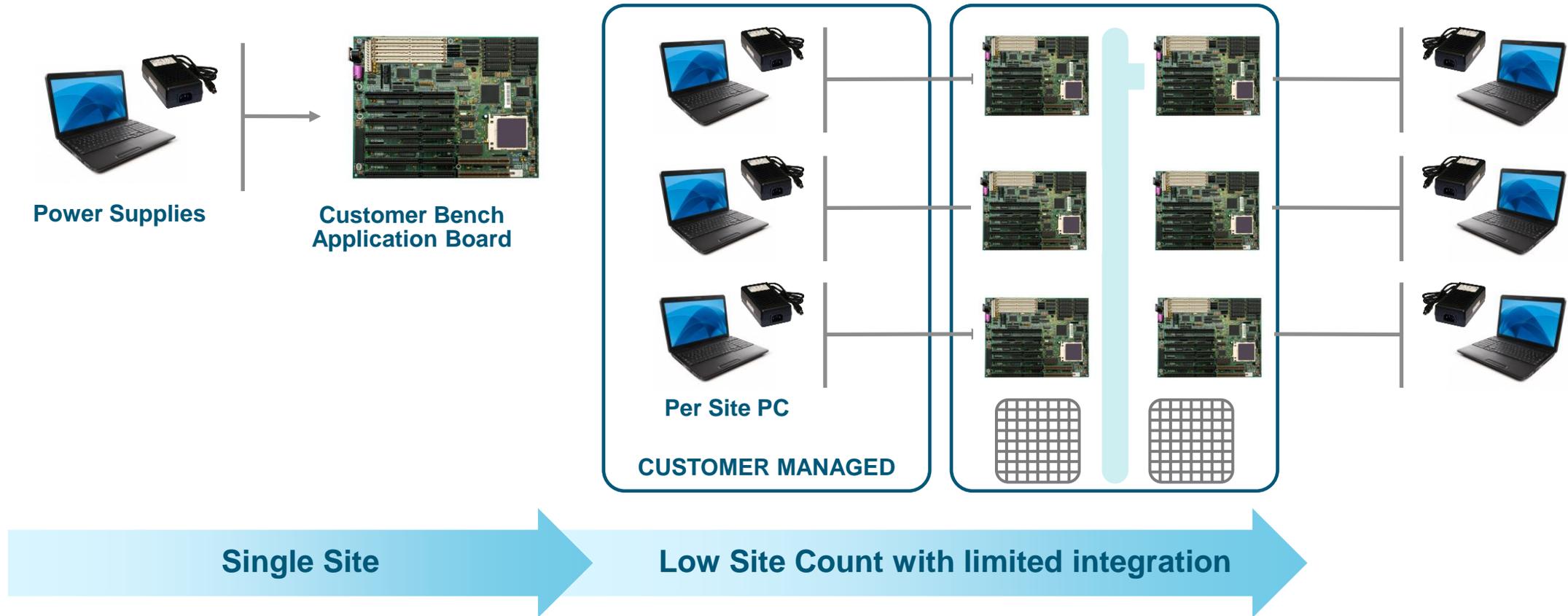
## Typical tests :

- Boot – 90% of failures from device maker are boot failures
- Play a video, run a graphics app, run a computing benchmark, simultaneously



**System level test ensures devices are tested similar to end user functionality  
SLT cannot and does not replace ATE testing**

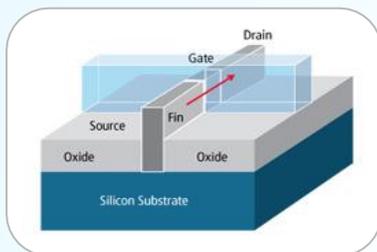
# What is Conventional System Level Test (SLT)?



**Conventional System Level Test Primarily Sampling Based  
Low Site Count Architecture Designed for “Sampling” and Low Volumes, Fixed Cost / Site**

# Customer Challenges lead to System Level Test

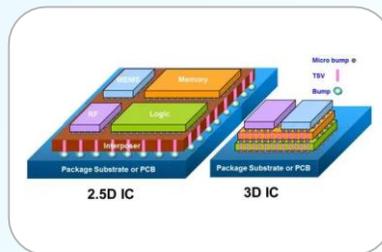
## NODE SHRINKAGE



**Increasing Transistor Count**

**Higher quality assurance**  
Even 99.5% test coverage leaves test escapes

## PACKAGING



**Complex 2.5D and 3D**

**Technology**  
Complex packaging limits ATE access

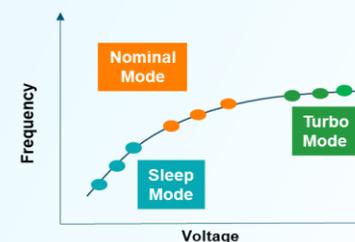
## SYSTEM



**Integration and User Scenarios**

**Higher quality assurance**  
Correct operation requires software interaction

## PROCESS



**Control PVT/ DVFS Explosions**

**Higher quality assurance** while managing and balancing test costs

## YIELD



**Reduce Overkill**

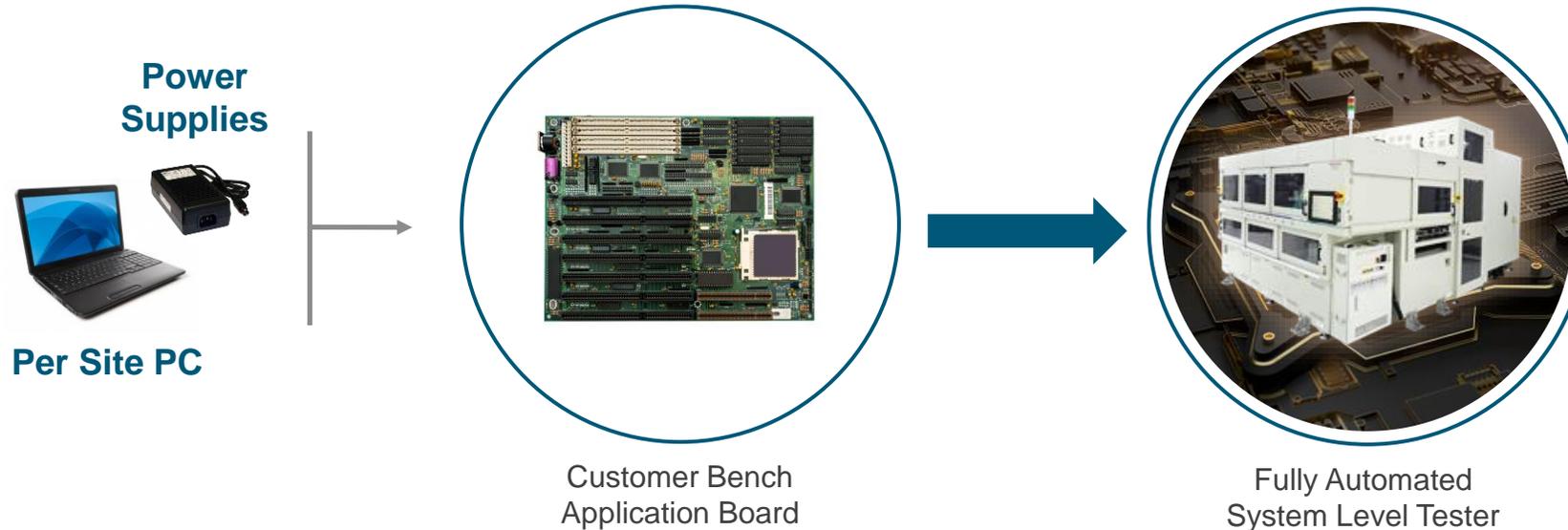
**Increase Yield**  
Guardbanding limits operating range while the part works well in the system

**All technological evolution calls for enhanced quality assurance**

# The Path to Massively Parallel System Level Test

## Advantest Industrial Automation of System Level Test

*System Level Test goes mainstream – it's here and Advantest makes it affordable at production scale*



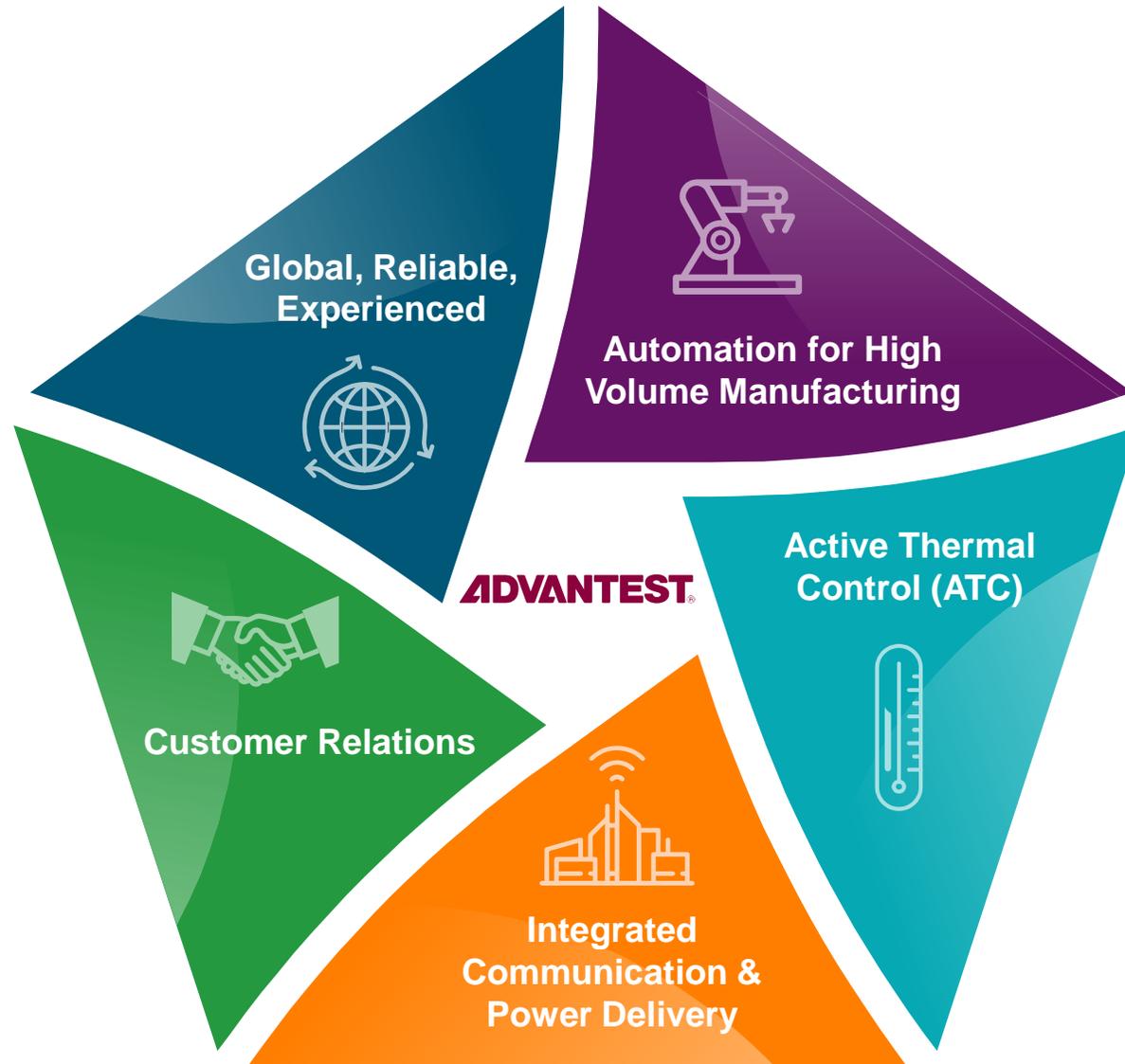
Fully automated system requires :

- Integrated communication & power delivery
- Thermal control
- High throughput handling
- Integrated Device interfaces

**Advantest has all technologies internally!**

**Advantest provides fully integrated and massively parallel system level test solutions  
The only truly global supplier delivering expected customer value**

# Key Advantages of Advantest Test Solutions



# Essai's Products Strengthen Advantest's value

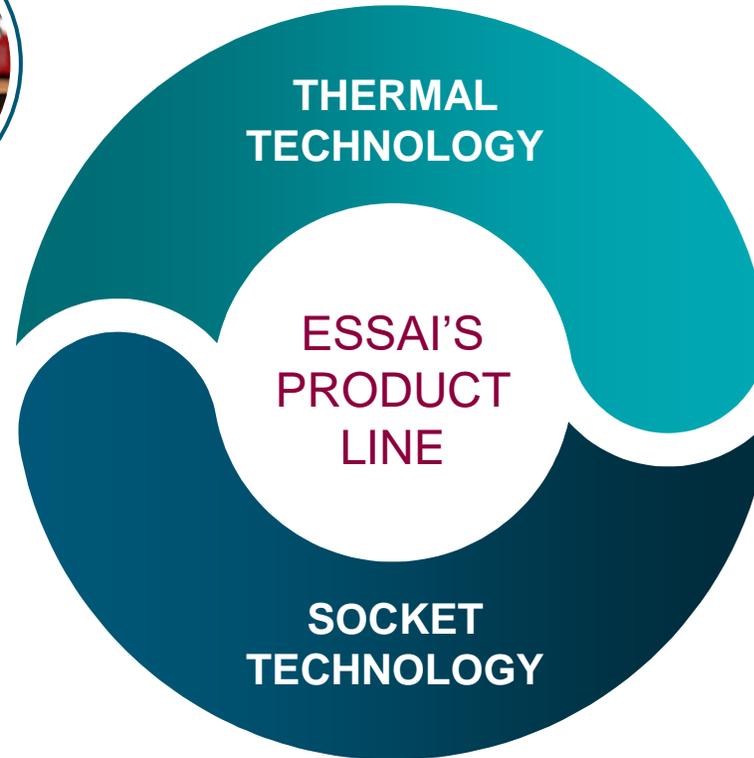
Next generation Peltier enables higher Yields

- Enables large form factors
- Higher heat density management
- Improved temperature control across wider ranges



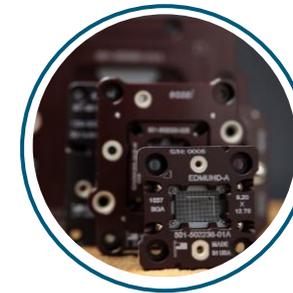
Bringing new innovative probe technologies to market:

- Patented full stack coaxial shielding technology
- Revolutionary Titan BGA probes with life-time CRES consistency



Modularized temperature control unit (TCU)

- DUT specific change kit
- Smarter serviceability design enabling higher uptime



Wide array of socketing technologies across:

- Package types
- Form factors
- Grid arrays & pitches



# Summary

All Rights Reserved - ADVANTEST CORPORATION

**ADVANTEST**<sup>®</sup>

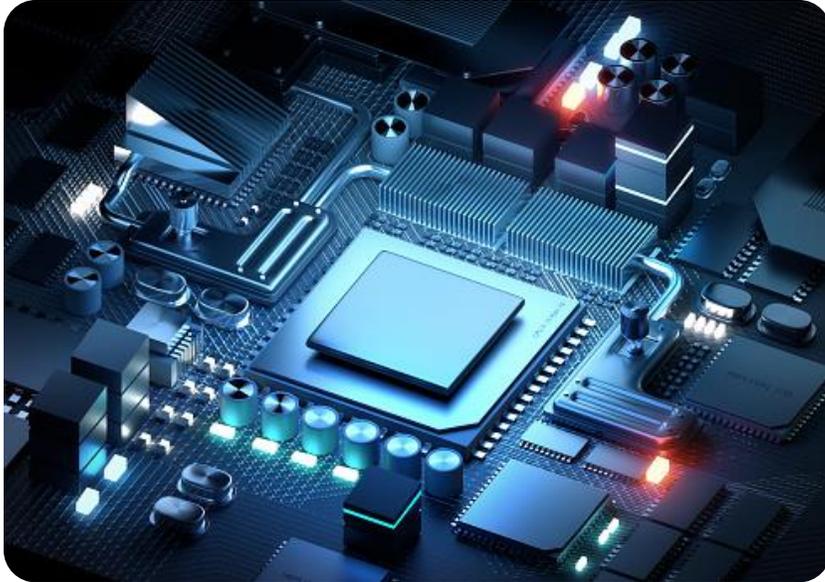
# Key Drivers of Market Growth



- Semiconductors are becoming more sophisticated and more complex, with larger capacity, which are driven by digital transformation
- All of these factors lead customer demand to ensure higher quality assurance by stringent testing
- Expect more customer interest for the combination of DFT and functional testing by ATE, real case performance testing by SLT, to maximize test coverage and improve quality

**Along with greater “Mission Critical” applications and semiconductor complexity, higher demand for quality assurance will continuously expand SLT market**

# Uniquely Positioned to Deliver Increased Value Across the Chain



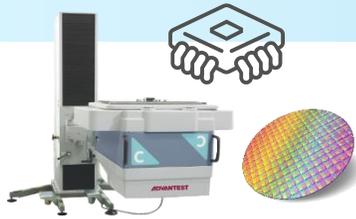
- As Data moves to the forefront, time-to-insight of the semiconductor test data grows increasingly more important
- Globally recognized as a leading global ATE supplier, Advantest continually delivers world class quality and reliability within a competitive cost envelope extended into SLT further improving customer value
- Advantest is uniquely positioned with fully integrated ATE and SLT solutions across the entire semiconductor test chain to link the important components

## Our Belief

A superior integrated technology position which fully integrates Advantest's tester, handler, thermal, socket, and data technologies is necessary to deliver upon and exceed customer value and expectations

# Advantest Uniquely Positioned Across Entire Test Life Cycle

## WAFER & PACKAGE TEST



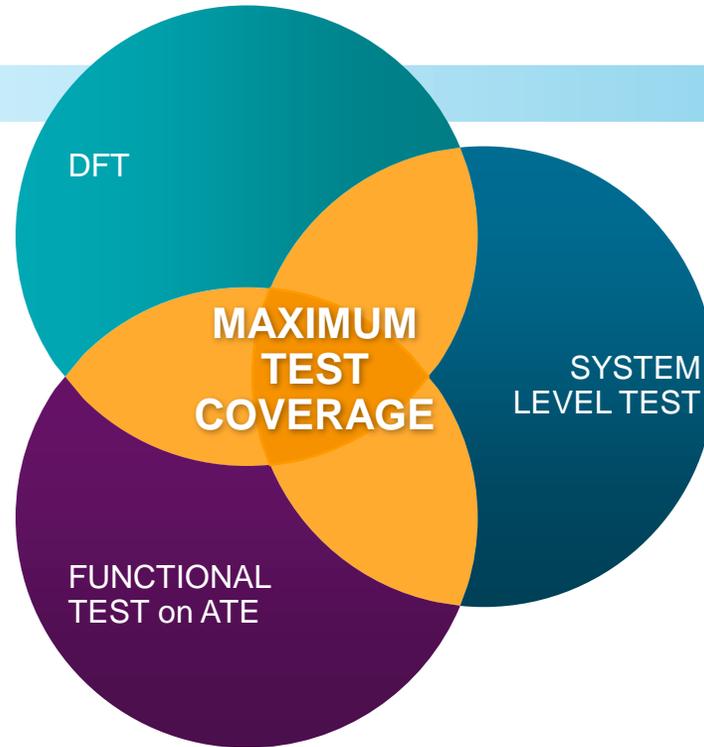
DFT & FUNCTIONAL TEST

In this presentation, DFT is referring structural test for ICs which include design for test architecture

## SYSTEM LEVEL TEST



SYSTEM PERFORMANCE TEST



ATE ensures design specs and is fabricated per the design

Combination of DFT, functional and SLT leads to maximum test coverage and best Time to Value

SLT ensures system performance of the final system